



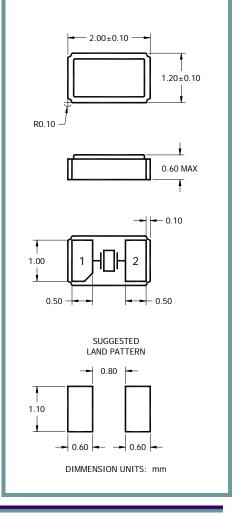
Product Features:

Low Cost SMD Package RoHS Compliant Compatible with Leadfree Processing Ultra Low Profile

Applications:

Real Time Clocks Metering Industrial Control Time Reference

Frequency	32.768 KHz		
ESR (Equivalent Series Resistance)	Less than 90 k Ω		
Shunt Capacitance (C0)	1.3 рҒ Тур.		
Motional Capacitance (CI)	6.5 fF Typ.		
Frequency Tolerance @ 25° C ±5°C	±20 ppm Standard		
Frequency Stability over Temperature	Parabolic -0.034 ppm / $^\circ$ C² Typ. Turnover point +25° ±5°C See Graph Below		
Crystal Cut	X-Cut		
Load Capacitance	12.5 pF Standard		
Drive Level	0.1 μW Typ., 0.5 μW Max.		
Aging	±5 ppm Max. / Year Standard		
Temperature			
Operating	-40° C to +85° C Standard		
Storage	-55° C to +125° C Standard		



Typical X Cut Temperature Coefficient					
0 -30 -60 E -90 E -120					
-150 -180	-40 -30 -20 -10 0 10 20 30 40 50 60 70 80 Temperature				

Part Number Guide		Sample Part Number:	IL3T - HX5F12.	5 - 32.768 KHz		
Package	Stability (ppm) at Room Temperature	Stability (ppm) over Operating Temperature	Operating Temperature Range	ode (overtone)	Load Capacitance (pF)	Frequency
IL3T -	H = ±20 ppm	X = X Cut	5 = -40°C to +85°C	F = Fundamental	12.5 pF Standard	- 32.768 KHz

CEOB2B晶振平台-全球最专业的晶振在线采购查询平台http://www.crystal95.com

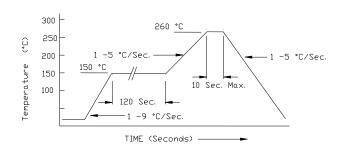


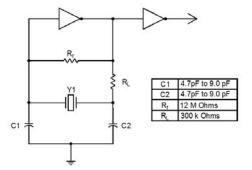
2 Pad Ceramic Base SMD Crystal, 2.0 mm x 1.2 mm



Pb Free Solder Reflow Profile:

Typical Circuit:



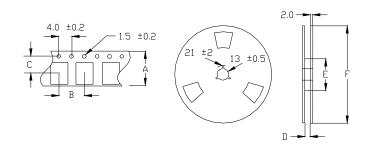


*Units are backward compatible with 240C reflow processes

Package Information:

MSL = 2 Termination = e1 (Sn/Cu/Ag over Ni over Kovar base metal)

Tape and Reel Information:



Quantity per Reel	3000
Α	8.0 ±0.2
В	4.0 ±0.1
С	3.5 ±0.05
D	9.0 ±0.3
E	60 / 80
F	180 / 250

Environmental Specifications

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10-8 atm cc/s
Solvent Resistance	MIL-STD-202, Method 215

Marking

Line 1: Frequency, Date Code

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